ThermalTIG0350Œý?îGFP

LDSA2 2025.11



Thermal TIG0350Œ5. ÿHÌ v6 MK—-¥o M?ìe:Eƒ*û?ìGDP o "î`ÆD' NP"o!6Eƒ4¸. <•X…&'"Ð?ì%g õ1 O 4b?ì%gWgfao WÄ`L# "î ä\ÞDKfa.a 1 Qn(|Eƒ<¥=~o eL MKúMÞEƒ2¤Xå?ìe:o ÍO 2Ïi×4b?ì4GB† <Zä ¦#À"î&' -7=(Fì6 §*Wo -u&'i×=(%ù" .a1 v6 .8/&Eƒ&ªAF.

Thermal TIG0350 is a kind of thermal grease material with low viscosity and low thermal resistance. The material can be applied on heating devices and heat spreader surfaces by screen printing. Due to good wetting between the interfaces after assembly, the contact thermal resistance will be substantially reduced to improve heat dissipation efficiency. This product can be stored at RT for short-term and cured at elevated temperature to form elastic pad.

FeaturesAz/(

- zLowThermal ResistanceM?ìe:
- zLowViscosity MK—-¥
- zHighReliability i×"îf_/&
- zScreenPrinting NP"o!6

Applications ¨#Â-•D)

- zLaptop CPUJ Z¯6+D4P CPU
- zCommunication equipment _ Z®Z½(
- zPower supply controller D4=•2¦!5KúMÞ
- zADAS5yOüi}iuKúMÞ

Property Az/(	Typical Value y&Œ =	Unit "V N	Test Method <LZÖ4º;Ö
Composition <X,1 !	Silicone Filled with Thermal Powder GDOõ%Ù?ìKˆ R		—
Color g•Qs	BlueSÜQq	—	Visual EíXÅ
Thermal Conductivity *ý?îKü4q Thermal	3.5	W/m·K	ASTM D5470

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and need to take all the risks and responsibilities to use.

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